ABSTRACT OF THE DISCLOSURE

The photosensitive resin composition is composed of a poly((meth)acrylic acid)-based water-soluble photo-sensitive resin (A) having an acid value of 150 mgKOH/g or more on a solid basis; the resin (A) being formed of a ((meth)acrylic acid)-based polymer in which a compound represented by formula (1):

$$\begin{array}{c|c}
& O \\
& H_2C \\
& C \\
& C$$

(wherein R^1 represents H or Me; and R^2 represents a liner or branched C2-C10 alkylene group) has been added to portions of the carboxylic groups, a photopolymerization initiator (B); and water (C).